





### **RT2 – LET calculation, ions penetration**

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## Main problems to discuss

- Various LET calculation methods.
- Range effects:
  - LET modifications due to DUT overlayers.
  - LET calculation at sensitive volume level (deep located sensitive volumes or back-side irradiation).
- Other problems when performing HI tests



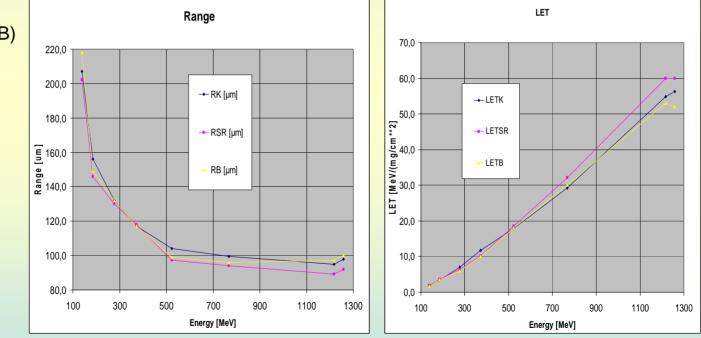
# Various LET/range calculation tools



#### • SRIM, TRIM, Kantele, Hubert & al.,...

#### =>some non negligible differences!!!

e.g.: Kantele (K) vs SRIM (S) & BNL LET calculator (B)



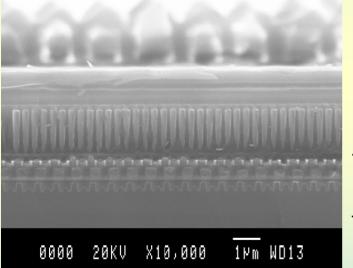
Is it possible to harmonize the LET/ range calculation methods?



# LET calculation at sensitive volume level

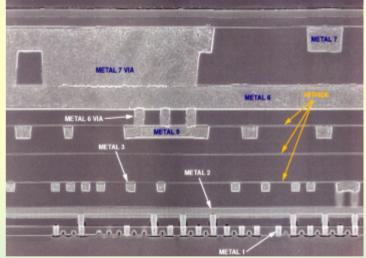


 Front side irradiation: Overlayer materials are not taken into account when calculating LET and range.



<< 256Mb SDRAM (vertical storage capacitor).

Planar Copper >> 7 Metal layers Damascene technology



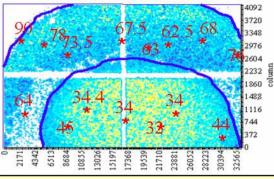
 Backside irradiation: After thinning, the die thickness may vary all over the DUT surface (a few µm only with up-to-date techniques). This shall be taken into account when choosing the ion.

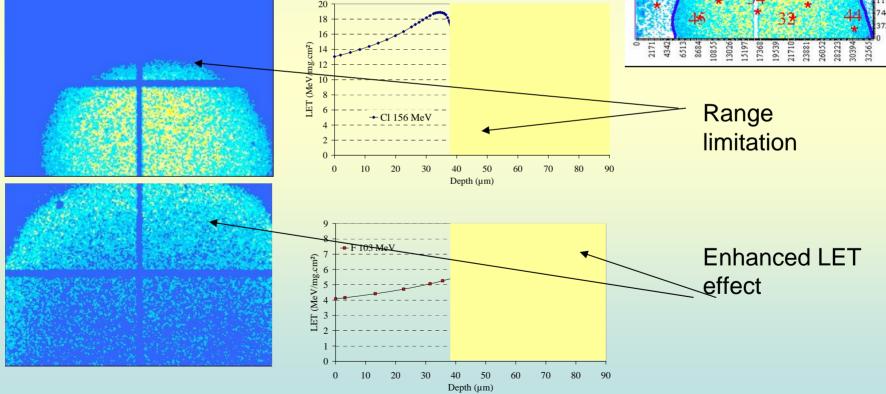


# LET calculation at sensitive volume level



Backside irradiation of 256Mbit SDRAM (2001) => Worst case: important thickness variation and limited beam range.



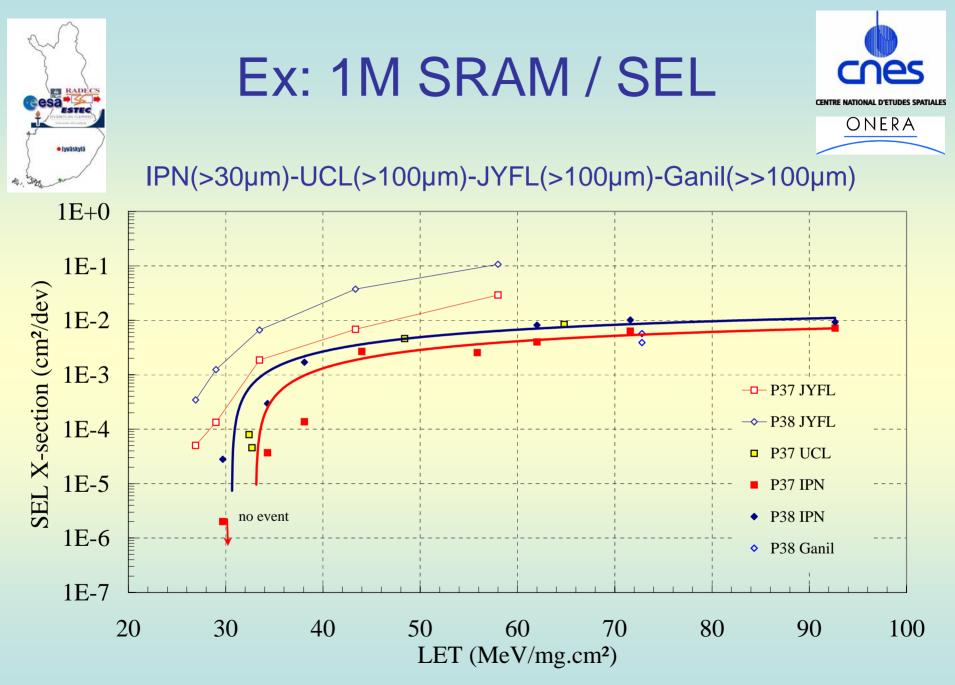




## Other problems



- Particle monitoring X-check between accelerators
  - Reproductibility between accelerators (Differences can be observed even when testing the same DUT with the same test system and similar LET and range).
  - Reproductibility between test campaigns at the same facility.
- ⇒Is the problem due to LET/range, dosimetry (counting, homogeneity, beam purity)?





### Beams LET/range comparison



ONERA

